



Temperature Sensing MOSFET, N-Channel 40-V (D-S)

FEATURES

- Temperature-Sense Diodes for Thermal Shutdown
- TrenchFET® Power MOSFET
- 175°C Maximum Junction Temperature
- ESD Protected: 2000 V
- Logic-Level Low On-Resistance
- Avalanche Rated
- Low Gate Charge
- Fast Turn-On Time
- 100% R_g Tested
- 5-Lead D²PAK

APPLICATIONS

- Automotive
- Industrial

PRODUCT SUMMARY

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
40	0.009 @ $V_{GS} = 10$ V	60 ^a
	0.012 @ $V_{GS} = 4.5$ V	60

Notes

a. Package Limited

DESCRIPTION

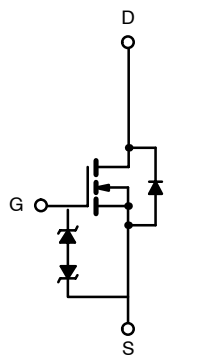
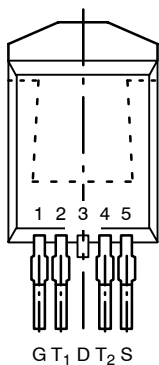
The SUM60N04-12LT is a 40-V n-channel, 15-m Ω logic level MOSFET in a 5-lead D²PAK package built on the Vishay Siliconix proprietary high-cell density TrenchFET technology.

Two anti-parallel electrically isolated poly-silicon diodes are used to sense the temperature changes in the MOSFET.

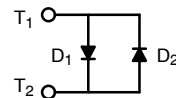
The gate of the MOSFET is protected from high voltage transients by two back-to-back poly-silicon zener diodes.

FUNCTIONAL BLOCK DIAGRAM AND PIN CONFIGURATION

D²Pak
TO-263, 5 Leads



N-Channel MOSFET



Ordering Information: SUM60N04-12LT
SUM60N04-12LT-E3 (Lead Free)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 20	
V_{GS} Clamp Current		I_G	50	mA
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	60 ^a	A
	$T_C = 100^\circ\text{C}$		50	
Avalanche Current		I_{AR}	50	
Repetitive Avalanche Energy	$L = 0.1\text{ mH}$	E_{AR}	125	mJ
Source-to-Anode Voltage		V_{SA}	100	V
Source-to-Cathode Voltage		V_{SC}	100	
Maximum Power Dissipation ^a	$T_C = 25^\circ\text{C}$	P_D	110	W
	$T_A = 25^\circ\text{C}^d$		3.75	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Limit	Unit
Junction-to-Ambient ^d	R_{thJA}	40	$^\circ\text{C/W}$
Junction-to-Case	R_{thJC}	1.35	

Notes:

- Package limited.
- Duty Cycle $\leq 1\%$.
- See SOA curve for voltage derating.
- When mounted on 1-inch square PCB FR4.

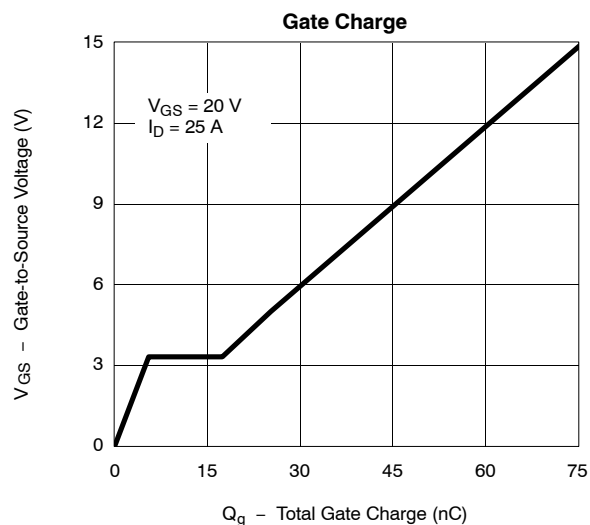
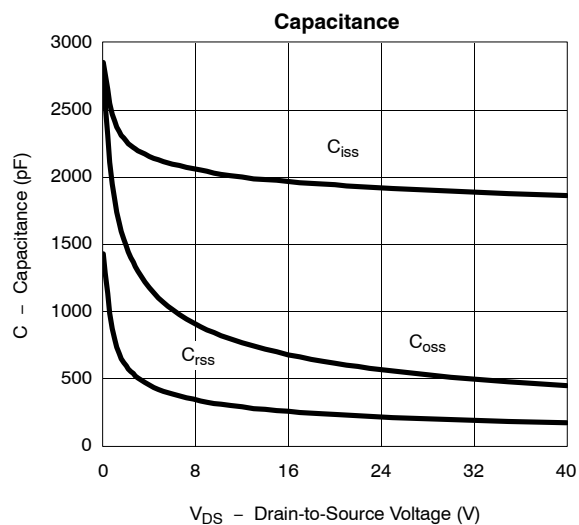
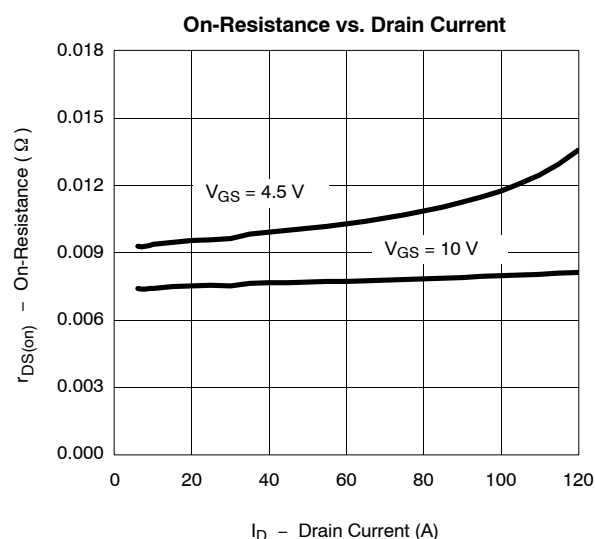
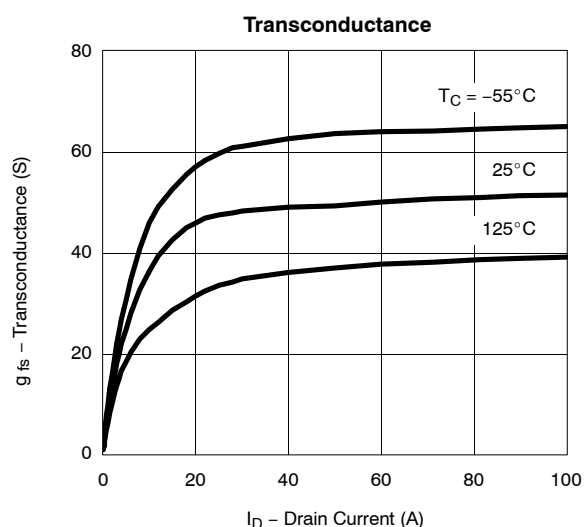
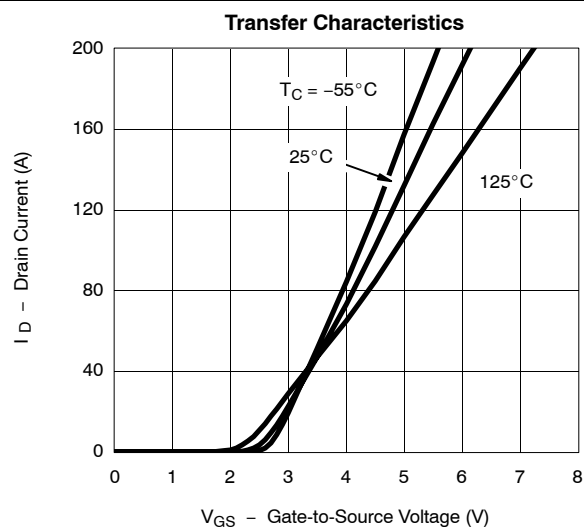
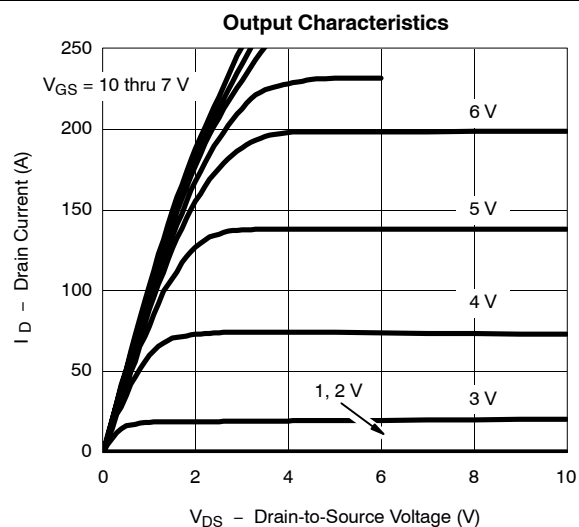


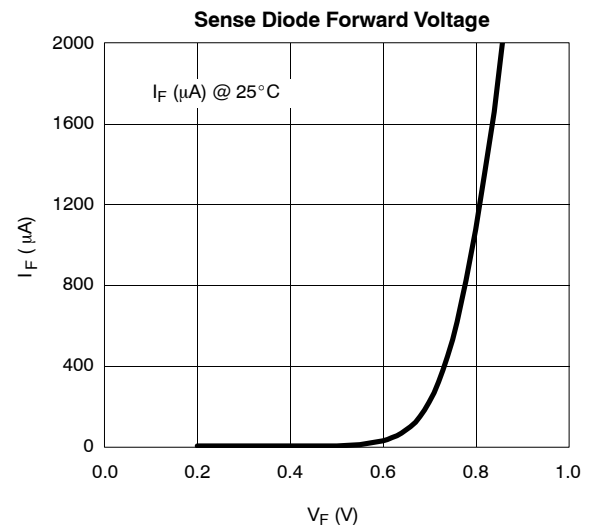
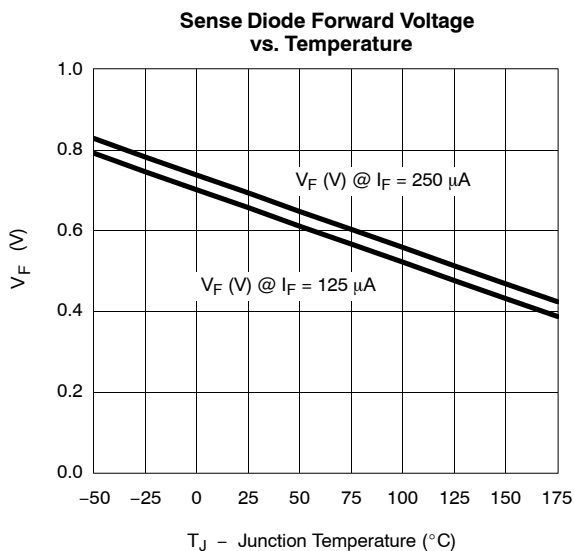
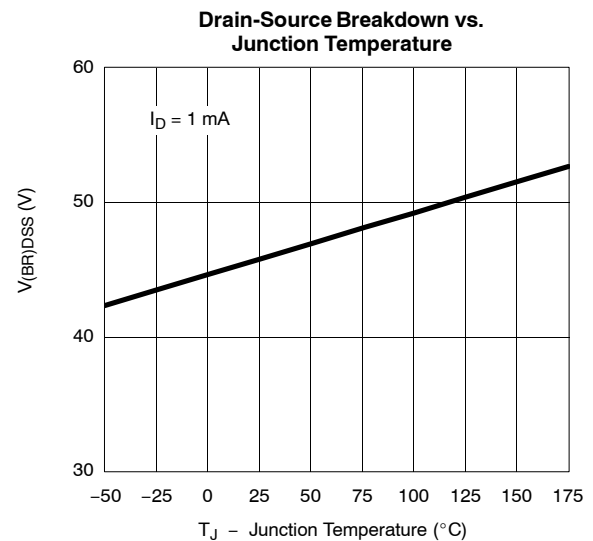
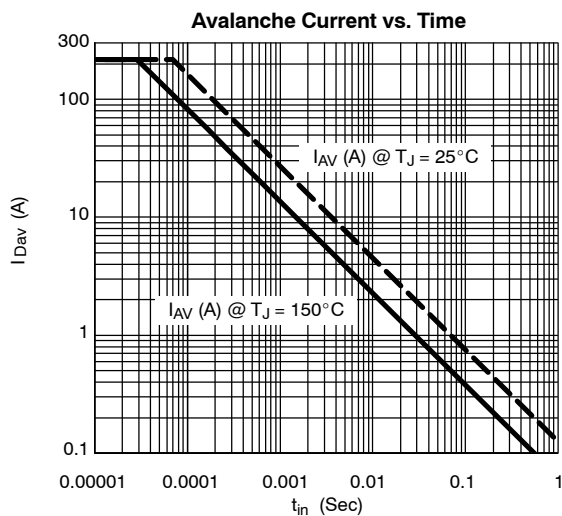
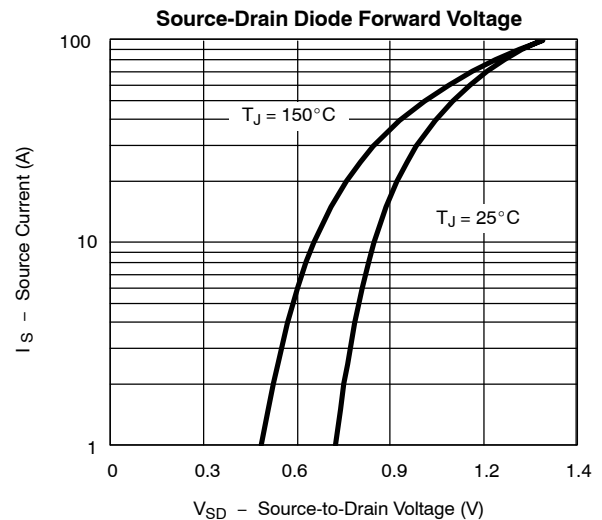
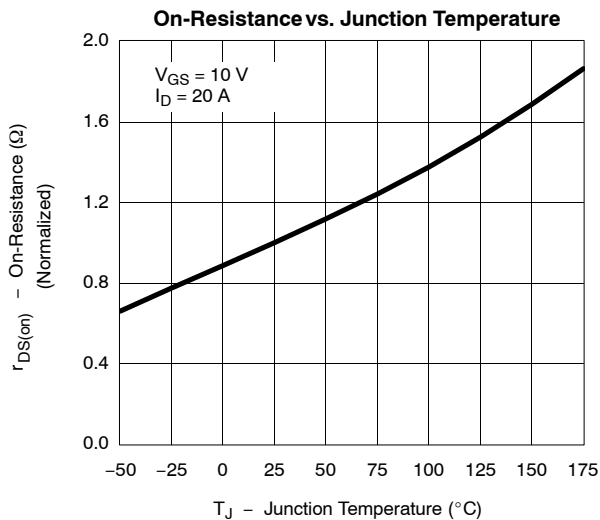
MOSFET SPECIFICATIONS (T _J =25° C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	40			V
V _{GS} Clamp Voltage	V _{GS}	V _{DS} = 0 V, I _G = 20 μA	10		20	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _{DS} = 1 mA	1		2	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 5 V			± 250	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 125° C			50	
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 175° C			250	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.0075	0.009	Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125° C			0.0135	
		V _{GS} = 10 V, I _D = 20 A, T _J = 175° C			0.018	
		V _{GS} = 4.5 V, I _D = 20 A		0.0095	0.012	
Sense Diode Forward Voltage	V _{FD1}	I _F = 250 μA	675		735	mV
	V _{FD2}	I _F = 250 μA	675		735	
Sense Diode Forward Voltage Increase	ΔV _F	From I _F = 125 μA to I _F = 250 μA	25		50	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 20 A		35		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		1920		pF
Output Capacitance	C _{oss}			560		
Reverse Transfer Capacitance	C _{rss}			210		
Total Gate Charge ^c	Q _g	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 25 A		51	70	nC
Gate-Source Charge ^c	Q _{gs}			5.5		
Gate-Drain Charge ^c	Q _{gd}			12		
Gate Resistance	R _g		1.2		4.1	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 20 V, R _L = 0.8 Ω I _D = 25 A, V _{GEN} = 10 V, R _g = 2.5 Ω		20	40	ns
Rise Time ^c	t _r			70	120	
Turn-Off Delay Time ^c	t _{d(off)}			35	70	
Fall Time ^c	t _f			20	40	
Source-Drain Diode Ratings and Characteristics (T _C = 25° C) ^b						
Continuous Current	I _S				60	A
Pulsed Current	I _{SM}				240	
Forward Voltage ^a	V _{SD}	I _F = 60 A, V _{GS} = 0 V			1.4	V
Reverse Recovery Time	t _{rr}	I _F = 60 A, di/dt = 100 A/μs		40	60	ns

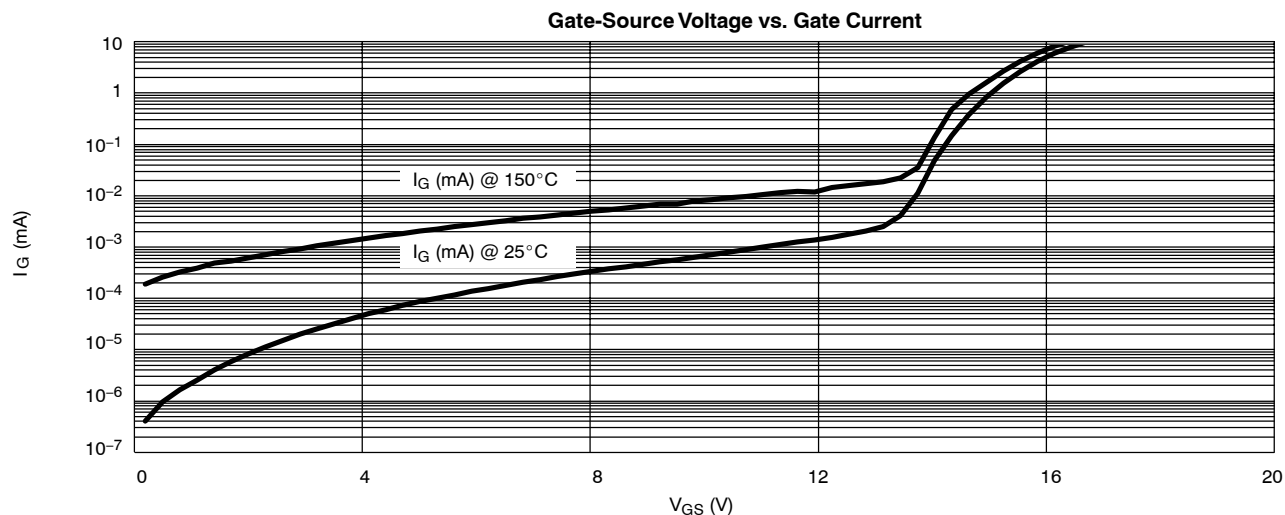
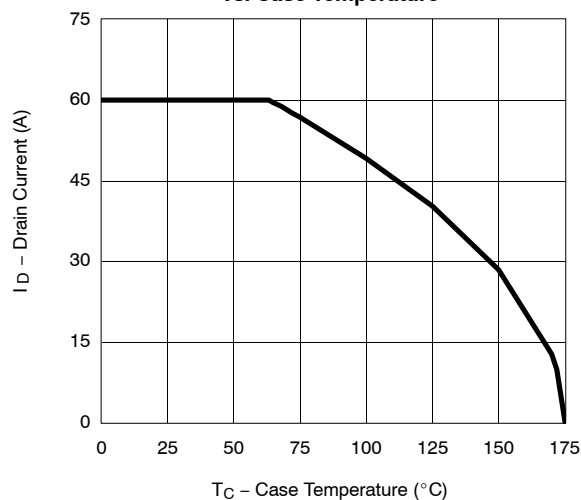
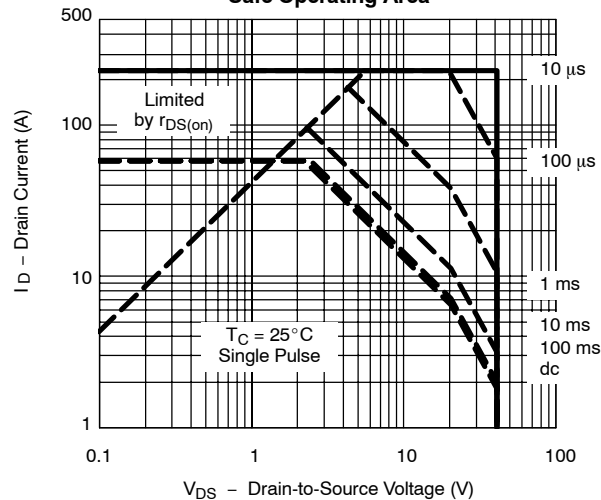
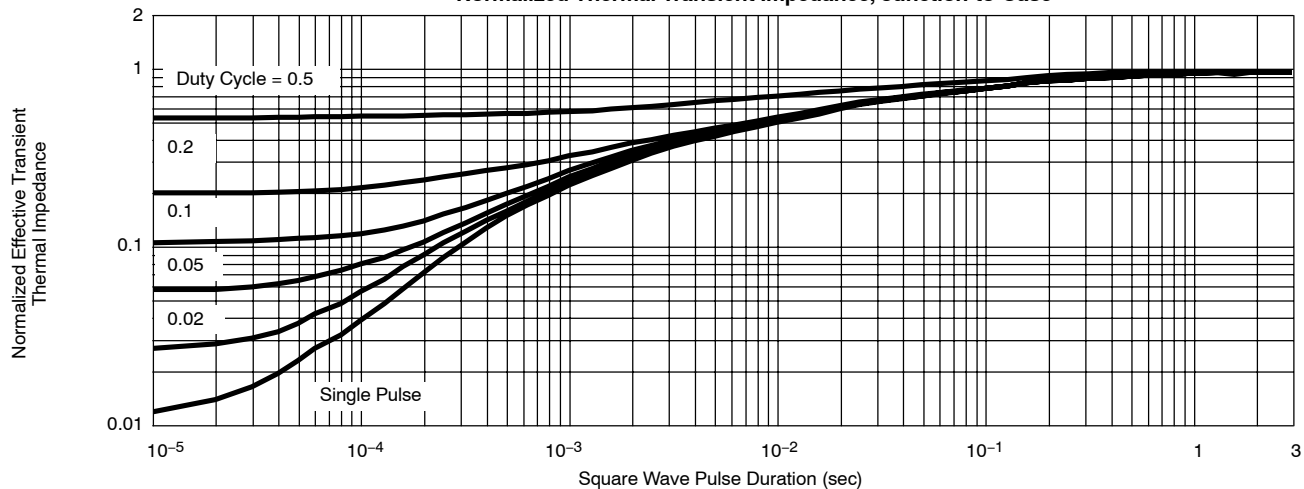
Notes:

- a Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b Guaranteed by design, not subject to production testing.
c Independent of operating temperature.

TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)



**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

TYPICAL CHARACTERISTICS OF G-S CLAMPING DIODES (25°C UNLESS NOTED)

THERMAL RATINGS
Maximum Avalanche and Drain Current vs. Case Temperature

Safe Operating Area

Normalized Thermal Transient Impedance, Junction-to-Case


APPLICATIONS

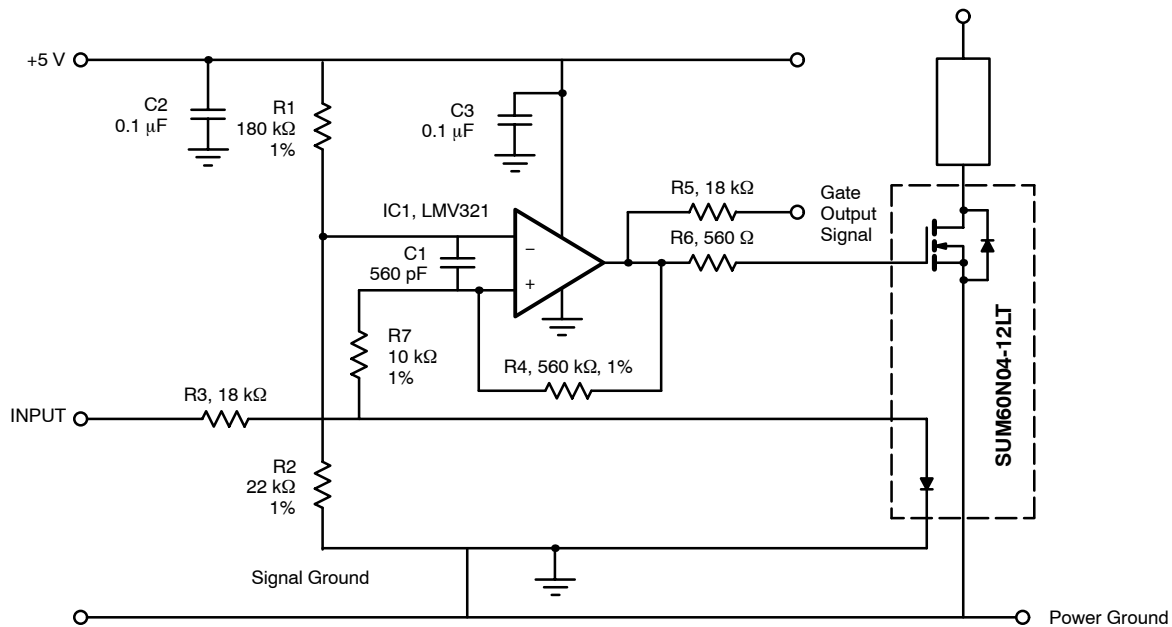


FIGURE 1.

The SUM60N04-12LT provides a non-committed diode to allow temperature sensing of the actual MOSFET chip. The addition of one simple comparator and a few other components is all that is required to implement a temperature protected MOSFET. Since it has a very tight tolerance on forward voltage, the forward voltage of the diode can be used to provide a shutdown signal. The diode forward voltage falls to around 0.4 V with a bias current of 250 μ A when the MOSFET chip is close to the maximum permitted temperature value. The external comparator used to detect over temperature can also be used as a driver stage for the MOSFET, meaning that the on/off input is logic compatible, and can be driven from a logic gate.

A typical circuit is shown in Figure 1. Here a LMV321 operational amplifier is used to drive the MOSFET, and as a comparator to when the maximum junction temperature is reached. The circuit will turn on once more when the chip has cooled to approximately 110°C, and can cycle on and off until the fault is cleared or the power is removed. This circuit has assumed a 5-V rail is available, but the circuit could easily be adapted for a 12-V rail, for example.

The LMV321 op amp was selected to give reasonable output current to drive the MOSFET at a reasonable price. The SC-70 package means that the protection circuit uses very little board space. However the limited output current means that it can only be used in slow switching applications, where one microsecond switching time and limited dv/dt immunity can be

accepted. For PWM and other faster applications, a buffer should be added to drive the MOSFET, or the schematic in Figure 2 used to give fast switching speed.

The reference voltage for the trip point is derived from the 5-V rail, which should have reasonable voltage accuracy and stability (± 0.5 V). A voltage reference could be added if required, but the circuit is only intended to make the MOSFET invulnerable to drastic faults that might otherwise cause it to fail, not to give a precise shutdown point. 1% resistors are used to provide a reference voltage of 0.545 V, giving a nominal rising trip point of around 155°C, allowing for the hysteresis drop over R7.

A 560-pF capacitor across the inputs of the comparator provides some noise immunity and gives a response time of around a micro second, just faster than the switching speed of the MOSFET in this circuit (faster response has diminishing returns as the turn-off time is fixed). This does have a side effect of introducing such a delay at turn-on. If this is an issue (although if this delay is an issue, the switching time should be reviewed also), a separate driver could be added using a comparator for over temperature detection only as shown in Figure 2. The diode is then left biased whenever the power is applied to the load and there is no turn-on delay. In a very noisy environment C1 should be increased and additional capacitors may also be required from each input of the comparator to ground and on the logic input.

